

2022.3.1 News Release

Large Order for “Solder Ball Mounter” received from Overseas Major Semiconductor Package Substrate Manufacturer

We, AIMECHATEC, Ltd. (Head Office: Koyodai, Ryugasaki-shi, Ibaraki-pref. President: Isao Abe) are pleased to announce that we received large orders for full system line of “Solder Ball Mounter” including Inspection & Repair Equipment from Major Overseas Semiconductor Package Substrate Manufacturer.

Demands for Semiconductor Packages such as Data Center, Mobile Devices and In-vehicle applications have been expanding in the background of 5G Communication, Big Data, IoT and AI, etc. At the same time, stable quality and further improvement of Yield are required.

We have proposed new model G series incorporating High-Precision Alignment Technology as our core technology, and Printing Technology and know-how being cultivated for more than half a century. As a result, we received high praise and large orders.

For Advanced Semiconductor Packages such as FCBGA, MCU/MPU, 2.5/3D, and Fan-out, the needs for High Quality and High Yield are greater, and then our equipment that can improve Yield Rate is considered to be adopted.

We expect that this equipment will contribute to our further expansion of Semiconductor Businesses in the future.

We will continue to contribute to the society by improving convenient and affluent lifestyle through our technological innovations for manufacturing processes. Your continued kind support to our company is sincerely appreciated.

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